

# 128Kx16 SRAM/EEPROM MODULE

PRELIMINARY\*

## FEATURES

- Access Times of 35ns (SRAM) and 150ns (EEPROM)
- Access Times of 45ns (SRAM) and 120ns (EEPROM)
- Access Times of 70ns (SRAM) and 300ns (EEPROM)
- Packaging
  - 66 pin, PGA Type, 1.075" square HIP, Hermetic Ceramic HIP (H1) (Package 400)
  - 68 lead, Hermetic CQFP (G2T), 22mm (0.880") square (Package 509). Designed to fit JEDEC 68 lead 0.990" CQFJ footprint (Fig. 2)
- 128Kx16 SRAM
- 128Kx16 EEPROM
- Organized as 128Kx16 of SRAM and 128Kx16 of EEPROM Memory with separate Data Buses
- Both blocks of memory are User Configurable as 256Kx8
- Low Power CMOS
- Commercial, Industrial and Military Temperature Ranges

- TTL Compatible Inputs and Outputs
- Built-in Decoupling Caps and Multiple Ground Pins for Low Noise Operation
- Weight - 13 grams typical

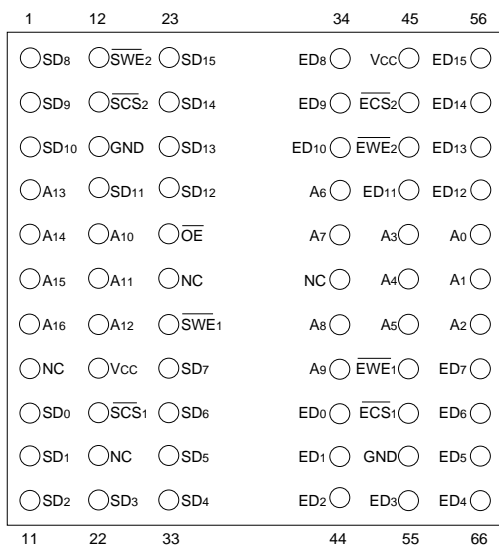
## EEPROM MEMORY FEATURES

- Write Endurance 10,000 Cycles
- Data Retention at 25°C, 10 Years
- Low Power CMOS Operation
- Automatic Page Write Operation
- Page Write Cycle Time 10ms Max.
- Data Polling for End of Write Detection
- Hardware and Software Data Protection
- TTL Compatible Inputs and Outputs

\* This data sheet describes a product under development, not fully characterized, and is subject to change without notice.

FIG. 1 PIN CONFIGURATION FOR WSE128K16-XH1X

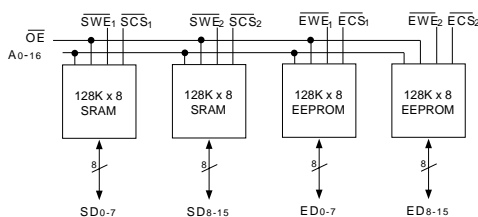
### TOP VIEW

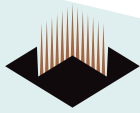


### PIN DESCRIPTION

ED0-15	EEPROM Data Inputs/Outputs
SD0-15	SRAM Data Inputs/Outputs
A0-16	Address Inputs
SWE <sub>1-2</sub>	SRAM Write Enable
SCS <sub>1-2</sub>	SRAM Chip Selects
OE	Output Enable
Vcc	Power Supply
GND	Ground
NC	Not Connected
EWE <sub>1-2</sub>	EEPROM Write Enable
ECS <sub>1-2</sub>	EEPROM Chip Select

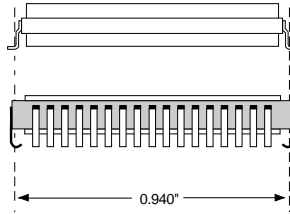
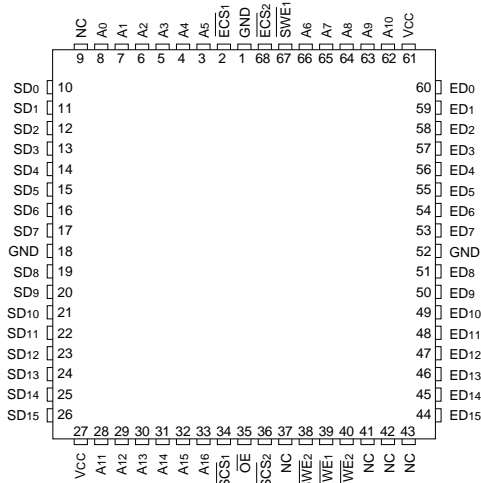
### BLOCK DIAGRAM





**FIG. 2 PIN CONFIGURATION FOR WSE128K16-XG2TX**

**TOP VIEW**

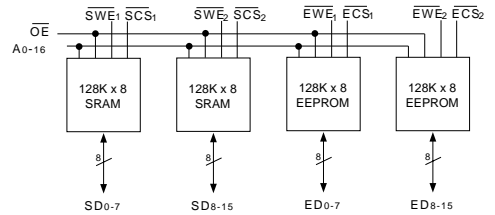


The WEDC 68 lead G2T CQFP fills the same fit and function as the JEDEC 68 lead CQFJ or 68 PLCC. But the G2T has the TCE and lead inspection advantage of the CQFP form.

**PIN DESCRIPTION**

ED0-15	EEPROM Data Inputs/Outputs
SD0-15	SRAM Data Inputs/Outputs
A0-16	Address Inputs
$\overline{SWE}_{1-2}$	SRAM Write Enable
$\overline{SCS}_{1-2}$	SRAM Chip Selects
$\overline{OE}$	Output Enable
Vcc	Power Supply
GND	Ground
NC	Not Connected
$\overline{EWE}_{1-2}$	EEPROM Write Enable
$\overline{ECS}_{1-2}$	EEPROM Chip Select

**BLOCK DIAGRAM**





## ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Operating Temperature	T <sub>A</sub>	-55	+125	°C
Storage Temperature	T <sub>STG</sub>	-65	+150	°C
Signal Voltage Relative to GND	V <sub>G</sub>	-0.5	V <sub>CC</sub> +0.5	V
Junction Temperature	T <sub>J</sub>		150	°C
Supply Voltage	V <sub>CC</sub>	-0.5	7.0	V

## CAPACITANCE

(T<sub>A</sub> = +25°C)

Parameter	Symbol	Conditions	Max	Unit
$\overline{OE}$ capacitance	C <sub>OE</sub>	V <sub>IN</sub> = 0 V, f = 1.0 MHz	50	pF
$\overline{WE}$ <sub>1-4</sub> capacitance HIP (PGA) CQFP G2T	C <sub>WE</sub>	V <sub>IN</sub> = 0 V, f = 1.0 MHz	20 20	pF
$\overline{CS}$ <sub>1-4</sub> capacitance	C <sub>CS</sub>	V <sub>IN</sub> = 0 V, f = 1.0 MHz	20	pF
Data I/O capacitance	C <sub>I/O</sub>	V <sub>I/O</sub> = 0 V, f = 1.0 MHz	20	pF
Address input capacitance	C <sub>AD</sub>	V <sub>IN</sub> = 0 V, f = 1.0 MHz	50	pF

This parameter is guaranteed by design but not tested.

## RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V <sub>CC</sub>	4.5	5.5	V
Input High Voltage	V <sub>IH</sub>	2.0	V <sub>CC</sub> + 0.3	V
Input Low Voltage	V <sub>IL</sub>	-0.3	+0.8	V
Operating Temp. (Mil.)	T <sub>A</sub>	-55	+125	°C

## EEPROM TRUTH TABLE

$\overline{CS}$	$\overline{OE}$	$\overline{WE}$	Mode	Data I/O
H	X	X	Standby	High Z
L	L	H	Read	Data Out
L	H	L	Write	Data In
X	H	X	Out Disable	High Z/Data Out
X	X	H	Write	
X	L	X	Inhibit	

## SRAM TRUTH TABLE

$\overline{SCS}$	$\overline{OE}$	$\overline{SWE}$	Mode	Data I/O	Power
H	X	X	Standby	High Z	Standby
L	L	H	Read	Data Out	Active
L	H	H	Read	High Z	Active
L	X	L	Write	Data In	Active

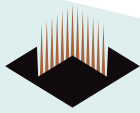
## DC CHARACTERISTICS

(V<sub>CC</sub> = 5.0V, V<sub>SS</sub> = 0V, T<sub>A</sub> = -55°C to +125°C)

Parameter	Symbol	Conditions	Min	Max	Unit
Input Leakage Current	I <sub>LI</sub>	V <sub>CC</sub> = 5.5, V <sub>IN</sub> = GND to V <sub>CC</sub>		10	μA
Output Leakage Current	I <sub>LO</sub>	$\overline{SCS}$ = V <sub>IH</sub> , $\overline{OE}$ = V <sub>IH</sub> , V <sub>OUT</sub> = GND to V <sub>CC</sub>		10	μA
SRAM Operating Supply Current x 16 Mode	I <sub>CCx16</sub>	$\overline{SCS}$ = V <sub>IL</sub> , $\overline{OE}$ = $\overline{ECS}$ = V <sub>IH</sub> , f = 5MHz, V <sub>CC</sub> = 5.5		360	mA
Standby Current	I <sub>SB</sub>	$\overline{ECS}$ = $\overline{SCS}$ = V <sub>IH</sub> , $\overline{OE}$ = V <sub>IH</sub> , f = 5MHz, V <sub>CC</sub> = 5.5		31.2	mA
SRAM Output Low Voltage	(35 to 45ns)	V <sub>OL</sub>	I <sub>OL</sub> = 8.0mA, V <sub>CC</sub> = 4.5	0.4	V
	(70ns)	V <sub>OL</sub>	I <sub>OL</sub> = 2.1mA, V <sub>CC</sub> = 4.5	0.4	V
SRAM Output High Voltage	(35 to 45ns)	V <sub>OH</sub>	I <sub>OH</sub> = -4.0mA, V <sub>CC</sub> = 4.5	2.4	V
	(70ns)	V <sub>OH</sub>	I <sub>OH</sub> = -1mA, V <sub>CC</sub> = 4.5	2.4	V
EEPROM Operating Supply Current x 16 Mode	I <sub>CC1</sub>	$\overline{ECS}$ = V <sub>IL</sub> , $\overline{OE}$ = $\overline{SCS}$ = V <sub>IH</sub>		155	mA
EEPROM Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 2.1 mA, V <sub>CC</sub> = 4.5V		0.45	V
EEPROM Output High Voltage	V <sub>OH1</sub>	I <sub>OH</sub> = 400 μA, V <sub>CC</sub> = 4.5V	2.4		V

### NOTES:

- The I<sub>CC</sub> current listed includes both the DC operating current and the frequency dependent component (@ 5 MHz). The frequency component typically is less than 2 mA/MHz, with  $\overline{OE}$  at V<sub>IH</sub>.
- DC test conditions: V<sub>IL</sub> = 0.3V, V<sub>IH</sub> = V<sub>CC</sub> - 0.3V



**SRAM AC CHARACTERISTICS**  
(V<sub>CC</sub> = 5.0V, GND = 0V, T<sub>A</sub> = -55°C to +125°C)

Parameter	Symbol	-35		-45		-70		Units
		Min	Max	Min	Max	Min	Max	
Read Cycle Time	t <sub>RC</sub>	35		45		70		ns
Address Access Time	t <sub>AA</sub>		35		45		70	ns
Output Hold from Address Change	t <sub>OH</sub>	0		0		3		ns
Chip Select Access Time	t <sub>ACS</sub>		35		45		70	ns
Output Enable to Output Valid	t <sub>OE</sub>		20		25		35	ns
Chip Select to Output in Low Z	t <sub>CLZ</sub> <sup>1</sup>	3		3		3		ns
Output Enable to Output in Low Z	t <sub>OLZ</sub> <sup>1</sup>	0		0		0		ns
Chip Disable to Output in High Z	t <sub>CHZ</sub> <sup>1</sup>		20		20		25	ns
Output Disable to Output in High Z	t <sub>OHZ</sub> <sup>1</sup>		20		20		25	ns

1. This parameter is guaranteed by design but not tested.

**SRAM AC CHARACTERISTICS**  
(V<sub>CC</sub> = 5.0V, GND = 0V, T<sub>A</sub> = -55°C to +125°C)

Parameter	Symbol	-35		-45		-70		Units
		Min	Max	Min	Max	Min	Max	
Write Cycle Time	t <sub>WC</sub>	35		45		70		ns
Chip Select to End of Write	t <sub>CW</sub>	25		30		60		ns
Address Valid to End of Write	t <sub>AW</sub>	25		30		60		ns
Data Valid to End of Write	t <sub>DW</sub>	20		25		30		ns
Write Pulse Width	t <sub>WP</sub>	25		30		50		ns
Address Setup Time	t <sub>AS</sub>	0		0		5		ns
Address Hold Time	t <sub>AH</sub>	0		0		5		ns
Output Active from End of Write	t <sub>OW</sub> <sup>1</sup>	4		4		5		ns
Write Enable to Output in High Z	t <sub>WHZ</sub> <sup>1</sup>		20		25		25	ns
Data Hold Time	t <sub>DH</sub>	0		0		0		ns

1. This parameter is guaranteed by design but not tested.

**FIG. 3**  
**AC TEST CIRCUIT**

The diagram shows a Device Under Test (D.U.T.) connected to a bridge circuit. The bridge consists of four diodes. Two current sources are connected to the top and bottom nodes of the bridge, with currents labeled I<sub>OL</sub> and I<sub>OH</sub>. A bipolar supply V<sub>Z</sub> ≈ 1.5V is connected across the bridge. An effective capacitance C<sub>eff</sub> = 50 pf is connected to the D.U.T. input.

**AC TEST CONDITIONS**

Parameter	Typ	Unit
Input Pulse Levels	V <sub>IL</sub> = 0, V <sub>IH</sub> = 3.0	V
Input Rise and Fall	5	ns
Input and Output Reference Level	1.5	V
Output Timing Reference Level	1.5	V

**NOTES:**  
V<sub>Z</sub> is programmable from -2V to +7V.  
I<sub>OL</sub> & I<sub>OH</sub> programmable from 0 to 16mA.  
Tester Impedance Z<sub>0</sub> = 75 Ω.  
V<sub>Z</sub> is typically the midpoint of V<sub>OH</sub> and V<sub>OL</sub>.  
I<sub>OL</sub> & I<sub>OH</sub> are adjusted to simulate a typical resistive load circuit.  
ATE tester includes jig capacitance.



FIG. 4 SRAM READ CYCLE

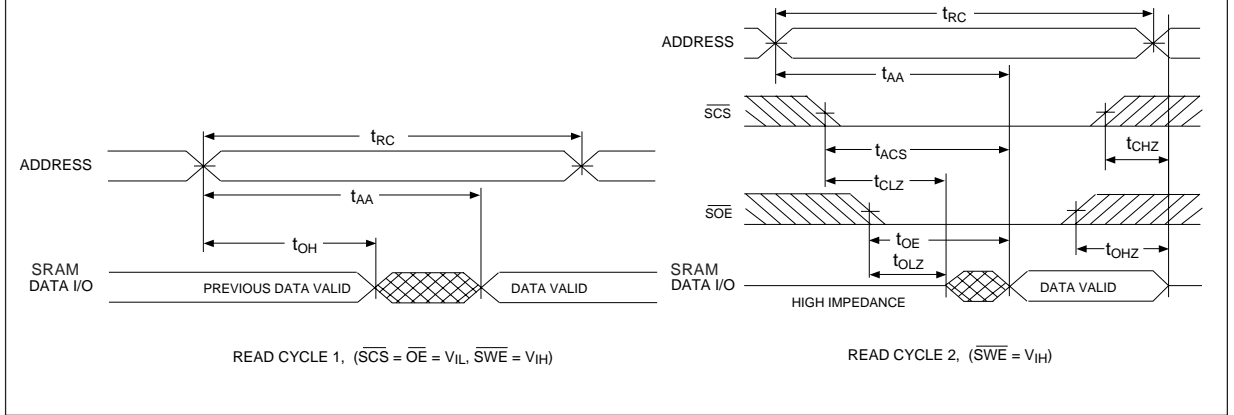


FIG. 5 SRAM WRITE CYCLE  
SWE CONTROLLED

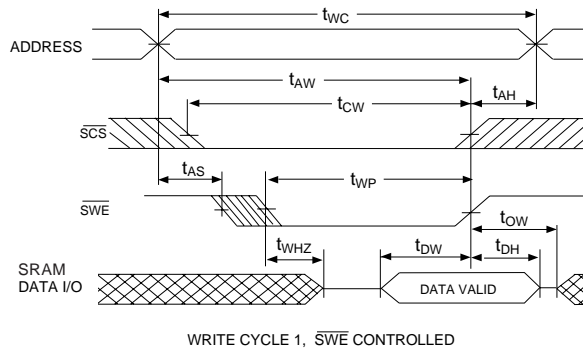
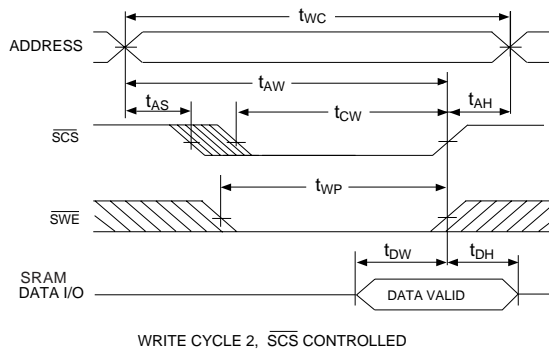


FIG. 6 SRAM WRITE CYCLE  
SCS CONTROLLED





EEPROM WRITE

A write cycle is initiated when OE is high and a low pulse is on EWE or ECS with ECS or EWE low. The address is latched on the falling edge of ECS or EWE whichever occurs last. The data is latched by the rising edge of ECS or EWE, whichever occurs first. A byte write operation will automatically continue to completion.

WRITE CYCLE TIMING

Figures 7 and 8 show the write cycle timing relationships. A write cycle begins with address application, write enable and chip select. Chip select is accomplished by placing the ECS line low. Write enable consists of setting the EWE line low. The write cycle begins when the last of either ECS or EWE goes low.

The EWE line transition from high to low also initiates an internal 150 μsec delay timer to permit page mode operation. Each subsequent EWE transition from high to low that occurs before the completion of the 150 μsec time out will restart the timer from zero. The operation of the timer is the same as a retriggerable one-shot.

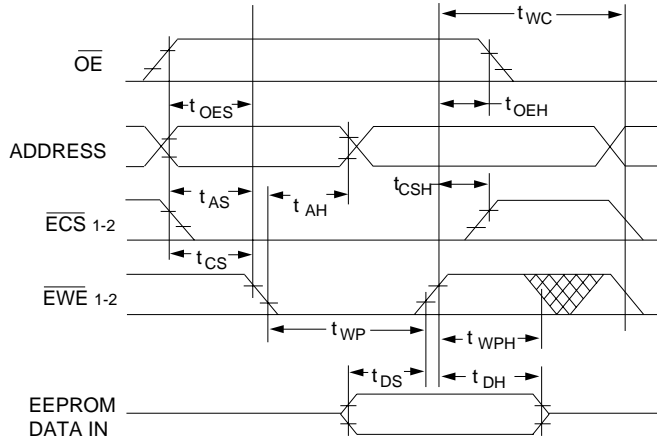
EEPROM AC WRITE CHARACTERISTICS

(VCC = 5.0V, VSS = 0V, TA = -55°C to +125°C)

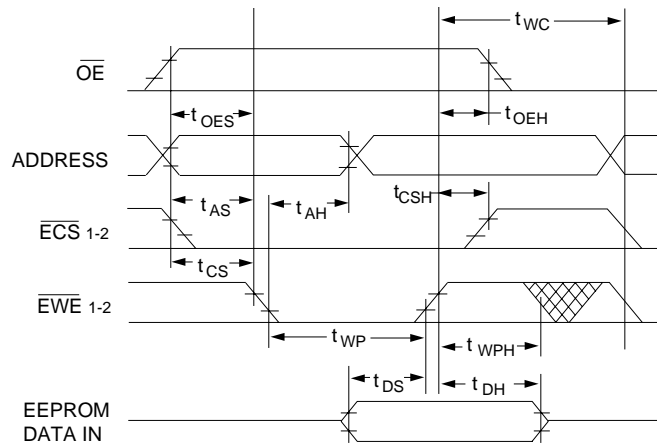
Table with 5 columns: Write Cycle Parameter, Symbol, Min, Max, Unit. Rows include Write Cycle Time, Address Set-up Time, Write Pulse Width, Chip Select Set-up Time, Address Hold Time, Data Hold Time, Chip Select Hold Time, Data Set-up Time, Output Enable Set-up Time, Output Enable Hold Time, Write Pulse Width High.



**FIG. 7** EEPROM WRITE WAVEFORMS  
EWE CONTROLLED



**FIG. 8** EEPROM WRITE WAVEFORMS  
 $\overline{ECS}$  CONTROLLED





**EEPROM READ**

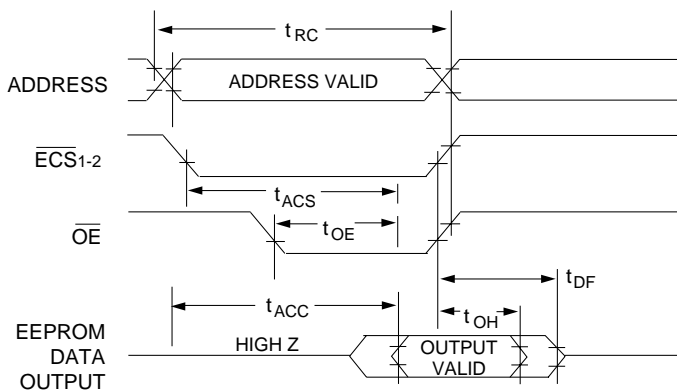
The WSE128K16-XXX EEPROM stores data at the memory location determined by the address pins. When  $\overline{ECS}$  and  $\overline{OE}$  are low and  $\overline{EWE}$  is high, this data is present on the outputs. When  $\overline{ECS}$  and  $\overline{OE}$  are high, the outputs are in a high impedance state. This two line control prevents bus contention.

**EEPROM AC READ CHARACTERISTICS**

( $V_{CC} = 5.0V, V_{SS} = 0V, T_A = -55^{\circ}C$  to  $+125^{\circ}C$ )

Read Cycle Parameter	Symbol	-120		-150		-300		Unit
		Min	Max	Min	Max	Min	Max	
Read Cycle Time	$t_{RC}$	120		150		300		ns
Address Access Time	$t_{ACC}$		120		150		300	ns
Chip Select Access Time	$t_{ACS}$		120		150		300	ns
Output Hold from Add. Change, $\overline{OE}$ or $\overline{ECS}$	$t_{OH}$	0		0		0		ns
Output Enable to Output Valid	$t_{OE}$	0	50	0	55	0	85	ns
Chip Select or $\overline{OE}$ to High Z Output	$t_{DF}$		70		70		70	ns

**FIG. 9 EEPROM READ WAVEFORMS**



**NOTES:**

$\overline{OE}$  may be delayed up to  $t_{ACS} - t_{OE}$  after the falling edge of  $\overline{ECS}$  without impact on  $t_{OE}$  or by  $t_{ACC} - t_{OE}$  after an address change without impact on  $t_{ACC}$ .





### EEPROM DATA POLLING

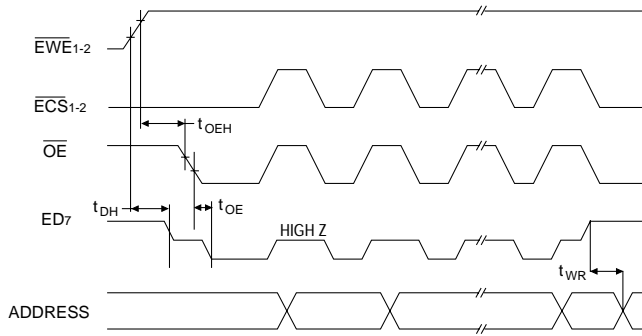
The WSE128K16-XXX offers a data polling feature for the EEPROM which allows a faster method of writing to the device. Figure 11 shows the timing diagram for this function. During a byte or page write cycle, an attempted read of the last byte written will result in the complement of the written data on D7 (for each chip.) Once the write cycle has been completed, true data is valid on all outputs and the next cycle may begin. Data polling may begin at any time during the write cycle.

### EEPROM DATA POLLING CHARACTERISTICS

(VCC = 5.0V, VSS = 0V, TA = -55°C to +125°C)

Parameter	Symbol	Min	Max	Unit
Data Hold Time	t <sub>DH</sub>	10		ns
$\overline{OE}$ Hold Time	t <sub>OEH</sub>	10		ns
$\overline{OE}$ To Output Valid	t <sub>OE</sub>		55	ns
Write Recovery Time	t <sub>WR</sub>	0		ns

FIG. 10 EEPROM DATA POLLING WAVEFORMS





### EEPROM PAGE WRITE OPERATION

The WSE128K16-XXX has a page write operation that allows one to 128 bytes of data to be written into the device and consecutively loads during the internal programming period. Successive bytes may be loaded in the same manner after the first data byte has been loaded. An internal timer begins a time out operation at each write cycle. If another write cycle is completed within 150µs or less, a new time out period begins. Each write cycle restarts the delay period. The write cycles can be continued as long as the interval is less than the time out period.

The usual procedure is to increment the least significant address lines from A0 through A6 at each write cycle. In this manner a page of up to 128 bytes can be loaded in to the EEPROM in a burst mode before beginning the relatively long interval programming cycle.

After the 150µs time out is completed, the EEPROM begins an internal write cycle. During this cycle the entire page of bytes will be written at the same time. The internal programming cycle is the same regardless of the number of bytes accessed.

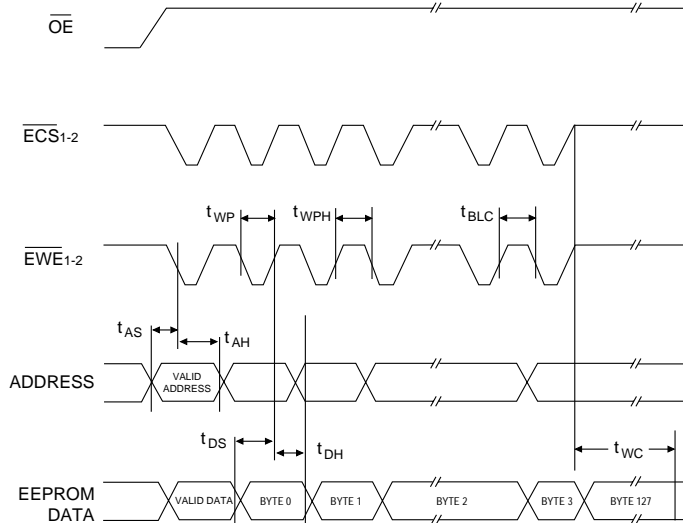
### EEPROM PAGE WRITE CHARACTERISTICS

(VCC = 5.0V, VSS = 0V, TA = -55°C to +125°C)

Page Mode Write Characteristics	Symbol	Min	Max	Unit
Write Cycle Time, TYP = 6ms	t <sub>WC</sub>		10	ms
Address Set-up Time	t <sub>AS</sub>	0		ns
Address Hold Time (1)	t <sub>AH</sub>	100		ns
Data Set-up Time	t <sub>DS</sub>	100		ns
Data Hold Time	t <sub>DH</sub>	10		ns
Write Pulse Width	t <sub>WP</sub>	150		ns
Byte Load Cycle Time	t <sub>BLC</sub>		150	µs
Write Pulse Width High	t <sub>WPH</sub>	50		ns

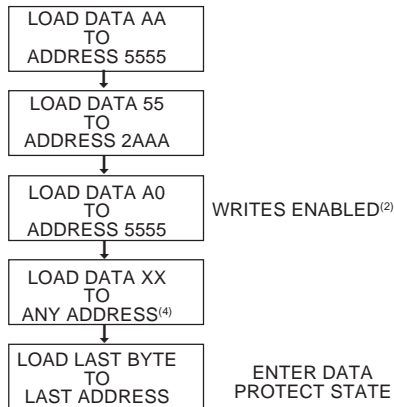
1. Page address must remain valid for duration of write cycle.

**FIG. 11**  
**EEPROM PAGE MODE**  
**WRITE WAVEFORMS**





**FIG. 12**  
**EEPROM SOFTWARE DATA PROTECTION**  
**ENABLE ALGORITHM<sup>(1)</sup>**

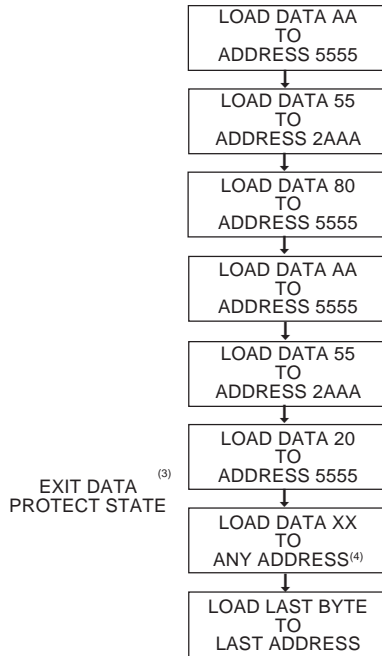


**NOTES:**

1. Data Format: ED<sub>7</sub> - ED<sub>0</sub> (Hex);  
Address Format: A<sub>16</sub> - A<sub>0</sub> (Hex).
2. Write Protect state will be activated at end of write even if no other data is loaded.
3. Write Protect state will be deactivated at end of write period even if no other data is loaded.
4. 1 to 128 bytes of data may be loaded.



**FIG. 13**  
**EEPROM SOFTWARE DATA PROTECTION**  
**DISABLE ALGORITHM<sup>(1)</sup>**



**NOTES:**

1. Data Format: ED<sub>7</sub> - ED<sub>0</sub> (Hex);  
Address Format: A<sub>16</sub> - A<sub>0</sub> (Hex).
2. Write Protect state will be activated at end of write even if no other data is loaded.
3. Write Protect state will be deactivated at end of write period even if no other data is loaded.
4. 1 to 128 bytes of data may be loaded.

**EEPROM SOFTWARE DATA PROTECTION**

A software write protection feature may be enabled or disabled by the user. When shipped by WEDC, the WSE128K16-XXX has the feature disabled. Write access to the device is unrestricted.

To enable software write protection, the user writes three access code bytes to three special internal locations. Once write protection has been enabled, each write to the EEPROM must use the same three byte write sequence to permit writing. After setting software data protection, any attempt to write to the device without the three-byte command sequence will start the internal write timers. No data will be written to the device, however, for the duration of twc. The write protection feature can be disabled by a six byte write sequence of specific data to specific locations. Power transitions will not reset the software write protection.

Each 128K byte block of the EEPROM has independent write protection. One or more blocks may be enabled and the rest disabled in any combination. The software write protection guards against inadvertent writes during power transitions, or unauthorized modification using a PROM programmer.

**EEPROM HARDWARE DATA PROTECTION**

These features protect against inadvertent writes to the WSE128K16-XXX. These are included to improve reliability during normal operation:

**a) Vcc power on delay**

As Vcc climbs past 3.8V typical the device will wait 5msec typical before allowing write cycles.

**b) Vcc sense**

While below 3.8V typical write cycles are inhibited.

**c) Write inhibiting**

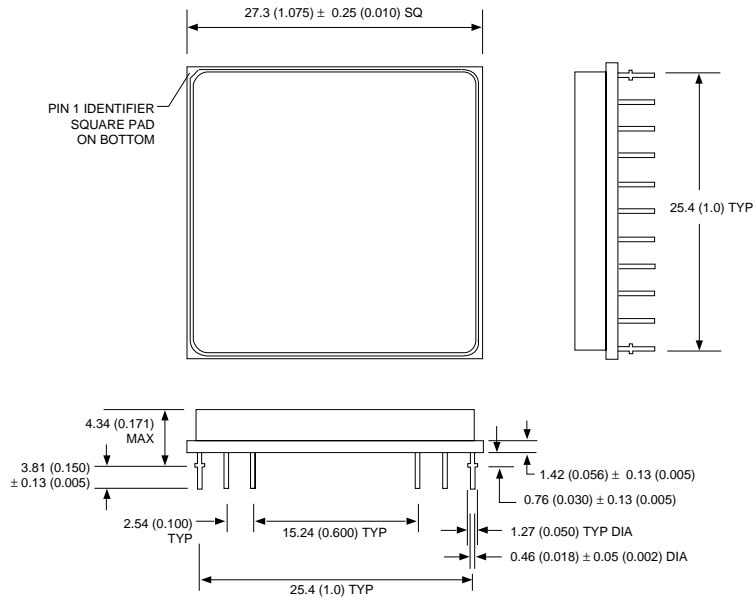
Holding OE low and either  $\overline{ECS}$  or  $\overline{EWE}$  high inhibits write cycles.

**d) Noise filter**

Pulses of <8ns (typ) on  $\overline{EWE}$  or  $\overline{ECS}$  will not initiate a write cycle.



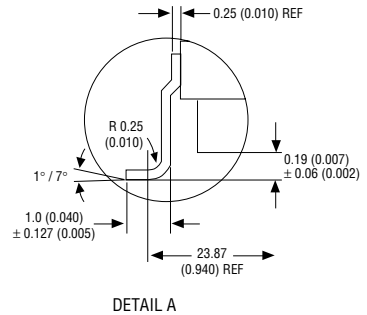
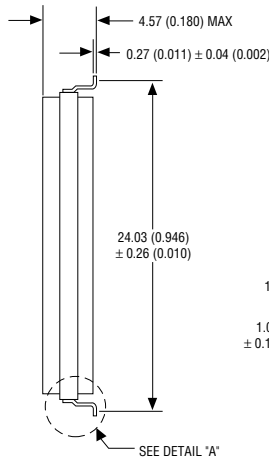
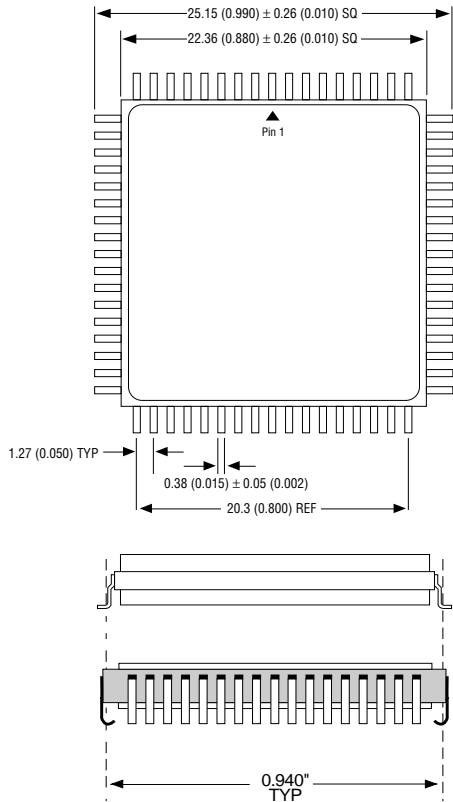
**PACKAGE 400: 66 PIN, PGA TYPE, CERAMIC HEX-IN-LINE PACKAGE, HIP (H1)**



ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES



**PACKAGE 509: 68 LEAD, CERAMIC QUAD FLAT PACK, CQFP (G2T)**



The WEDC 68 lead G2T CQFP fills the same fit and function as the JEDEC 68 lead CQFJ or 68 PLCC. But the G2T has the TCE and lead inspection advantage of the CQFP form.

ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES



**ORDERING INFORMATION**

**W S E 128K16 - XXX X X X**

**LEAD FINISH:**

- Blank = Gold plated leads
- A = Solder dip leads

**DEVICE GRADE:**

- M = Military Screened -55°C to +125°C
- I = Industrial -40°C to +85°C
- C = Commercial 0°C to +70°C

**PACKAGE TYPE:**

- H1 = 1.075" sq. Ceramic Hex-In-line Package, HIP (Package 400)
- G2T = 22.4mm Ceramic Quad Flat Pack, CQFP (Package 509)

**ACCESS TIME (ns)**

- 35 = 35ns SRAM and 150ns EEPROM
- 42 = 45ns SRAM and 120ns EEPROM
- 73 = 70ns SRAM and 300ns EEPROM

**ORGANIZATION, 128K x 16**

**EEPROM**

**SRAM**

**WHITE ELECTRONIC DESIGNS CORP.**